* This is advanced information and specifications 4,194,304 WORD x BIT DYNAMIC RAM are subject to change without notice.

DESCRIPTION

The TC514101J/Z is the new generation dynamic RAM organized 4,194,304 words by 1 The TC514101J/Z utilizes TOSHIBA's CMOS Silicon gate process technology as well as advanced circuit techniques to provide wide operating margins, both internally and to the system user. Multiplexed address inputs permit the TC514101J/Z to be packaged in a standard 26/20 pin plastic SOJ and 20 pin plastic ZIP. The package size provides high system bit densities and is compatible with widely available automated testing and insertion equipment. System oriented features include single power supply of 5V±10% tolerance, direct interfacing capability with high performance logic families such as Schottky TTL.

FEATURES

- 4,194,304 word by 1 bit organization
- · Fast access time and cycle time

		TC514101J	/z - 80/-10
^t RAC	RAS Access Time	80ns	100ns
t _{AA}	Column Address Access Time	40ns	50ns
tCAC	CAS Access Time	20ns	25ns
tRC	Cycle Time	150ns	180ns
tNC	Nibble Mode Cycle Time	40ns	45 ns

 Single power supply of 5V±10% with a built-in V_{BB} generator

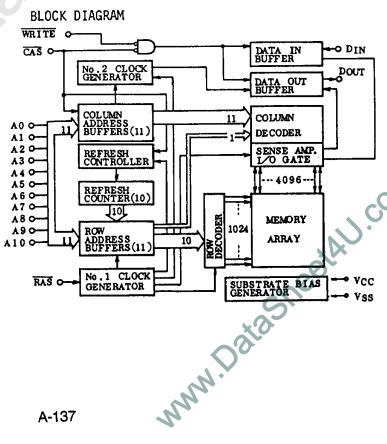
PIN CONNECTION (TOP VIEW)

Plasti	c SOJ	Plasti	c ZIP
DIN 1	26 J VSS	A9 11	2 CAS
WRITE 2	25 J DOUT	DOUT 3:	VSS
RAS 3	24 J CAS	DIN 5	6 WRITE
N.C. 14	23 J N.C.	RAS 7	8 A10
A10 05	22 J A9	N.C. 9:	10 N.C.
A0 09	18 1 A8	A2 13	12 A1
A1 010	17 1 A7		14 A3
A2 011	16 1 A6	VCC [15]	16 A4
A3 012	15 1 A5	A5 [17]	18 A6
VCC 13	14)1 14	A7 [19]	20 A8

PIN NAMES

Address Inputs
Row Address Strobe
Data In
Data Out
Column Address Strobe
Read/Write Input
Power (+5V)
Ground
No Connection

- . Low power
 - 578mW Operating (TC514101J/Z-80) 495mW Operating (TC514101J/Z-10) 5.5mW MAX. Standby
- · Output unlatched at cylce end allows two-dimensional chip selection
- Common I/O capability using "EARLY WRITE" operation
- · Read-Modify-Write, CAS before RAS refresh, RAS-only refresh, Hidden refresh, Nibble Mode and Test Mode capability
- All inputs and output TTL compatible
- 1024 refresh cycles/16ms
- Plastic SOJ: TC514101J Package Plastic ZIP: TC514101Z



ABSOLUTE MAXIMUM RATINGS

ITEM	SYMBOL	RATING	UNITS	NOTE
Input Voltage	VIN	-1 ∿ 7	V	1
Output Voltage	Vout	-1 ∿ 7	v	1
Power Supply Voltage	V _{CC}	-1 ∿ 7	v	1
Operating Temperature	TOPR	0 ∿ 70	°c	1
Storage Temperature	TSTG	-55 ∿ 150	°C	1
Soldering Temperature · Time	TSOLDER	260 • 10	°C•sec	1
Power Dissipation	PD	600	mW	1
Short Circuit Output Current	Iout	50	mA	1

RECOMMENDED DC OPERATING CONDITIONS (Ta=0 \sim 70 °C)

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT	NOTE
VCC	Supply Voltage	4.5	5.0	5.5	V	2
VIH	Input High Voltage	2.4	-	6.5	v	2
v_{IL}	Input Low Voltage	-1.0	_	0.8	V	2

DC ELECTRICAL CHARACTERISTICS (V_{CC}=5V±10%, Ta=0 ~ 70°C)

SYMBOL	PARAMETER		MIN.	MAX.	UNITS	NOTES
^I CC1	OPERATING CURRENT Average Power Supply Operating Current	TC514101J/Z-80		105	mA	3,4,5
	(RAS, CAS, Address Cycling: tRC=tRC MIN.)	TC514101J/Z-10	-	90	1	3,4,5
I _{CC2}	STANDBY CURRENT Power Supply Standby Current (RAS=CAS=VIH)		-	2	mA	
I _{CC3}	RAS ONLY REFRESH CURRENT Average Power Supply Current, RAS Only Mode	TC514101J/Z-80	-	105		
	(RAS Cycling, CAS=VIH: tRC=tRC MIN.)	TC514101J/Z-10	-	90	mA	3,5
I _{CC4}	NIBBLE MODE CURRENT Average Power Supply Current, Nibble Mode	TC514101J/Z-80				2 / 5
	(RAS=V _{IL} , CAS, Address Cycling: t _{NC} =t _{NC} MIN.)	TC514101J/Z-10			mA.	3,4,5
I _{CC5}	STANDBY CURRENT Power Supply Standby Current (RAS=CAS=V _{CC} -0.2V)		-	1	mA	
^I CC6	CAS BEFORE RAS REFRESH CURRENT Average Power Supply Current, CAS Before RAS	TC514101J/Z-80	-	105	mА	3
	Mode (RAS, CAS Cycling: t _{RC} =t _{RC} MIN.) INPUT LEAKAGE CURRENT	TC514101J/Z-10	***	90		,
I _{I(L)}	Input Leakage Current, any input $(0V \le V_{IN} \le 6$. Other Pins not under Test=0V)	5V, All	-10	10	μA	
¹ 0(L)	OUTPUT LEAKAGE CURRENT $(D_{OUT} \le 5.5V)$		-10	10	μA	
OH	OUTPUT LEVEL Output "H" Level Voltage (I _{OUT} 5mA)		2.4		v	· · ·
ו ז∩י	OUTPUT LEVEL Output "L" Level Voltage (I _{OUT} =4.2mA)		-	0.4	v	

ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS

 $(V_{CC}=5V\pm10\%, Ta=0 \sim 70$ °C) (Notes 6, 7, 8)

SYMBOL	PARAMETER		TC514101J/Z -80		TC514101J/Z -10		NOTES
011.00		MIN.	MAX.	MIN.	MAX.		
tRC	Random Read or Write Cycle Time	150	_ 3	180	-	ns	
t _{RMW}	Read-Modify-Write Cycle Time	175	_	210	-	ns	
^t NC	Nibble Mode Cycle Time	40	-	45	-	ns	
t _{NRMW}	Nibble Mode Read-Modify-Write Cycle Time	65	-	75	-	ns	
^t RAC	Access Time from RAS	1	80		100	ns	9,14,15
^t CAC	Access Time from CAS		20	-	25	ns	9,14
^t AA	Access Time from Column Address	-	40	-	50	ns	9,15
^t NCAC	Nibble Mode Access Time	-	20	-	25	ns	9
tCLZ	CAS to Output in Low-Z	0	•	0		ns	9
toff	Output Buffer Turn-off Delay	0	20 .	0	20	ns	10
tT	Transition Time (Rise and Fall)	3	50	3	. 50	ns	8
tRP	RAS Precharge Time	60	-	70	-	ns	
tRAS	RAS Pulse Width	80	10,000	100	10,000	ns	
tRSH	RAS Hold Time	20	-	25		ns	
tCSH	CAS Hold Time	80	-	100	-	ns	
tCAS	CAS Pulse Width	20	10,000	25	10,000	ns	
tRCD	RAS to CAS Delay Time	20	60	25	75	ns	14
tRAD	RAS to Column Address Delay Time	15	40	20	50	ns	15
tCRP	CAS to RAS Precharge Time	5	-	10		ns	
tCP	CAS Precharge Time	10		10		ns	
tASR	Row Address Set-Up Time	0	_	0	-	ns	ļ
t _{RAH}	Row Address Hold Time	10	-	15	-	ns	ļ
t _A SC	Column Address Set-Up Time	0	-	0	-	ns	ļ
t CAH	Column Address Hold Time	15	_	20	-	ns	ļ
tAR	Column Address Hold Time referenced to RAS	60	-	75	-	ns	ļ
tRAL	Column Address to RAS Lead Time	40	-	50	_	ns	<u> </u>
tRCS	Read Command Set-Up Time	0	-	0	-	ns	
^t RCH	Read Command Hold Time	0	<u> </u>	0	-	ns	11
t _{RRH}	Read Command Hold Time referenced to RAS	0	-	0	-	ns	11
tWCH	Write Command Hold Time	15		20		ns	
twcr	Write Command Hold Time referenced to RAS	60	-	75	-	ns	<u> </u>
tWP	Write Command Pulse Width	15		20	 	ns	ļ
tRWL	Write Command to RAS Lead Time	20	<u> </u>	25		ns	<u> </u>

TC514101J/Z-80 TC514101J/Z-10

ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS (Continued)

SYMBOL	PARAMETER		101J/Z 80		101J/Z 10	UNITS	NOTES
<u> </u>		MIN.	MAX.	MIN.	MAX.]	
t CWL	Write Command to CAS Lead Time	20	-	25		ns	
tDS	Data Set-Up Time	0		0	_	ns	12
^t DH	Data Hold Time	15	-	20	_	ns	12
^t DHR	Data Hold Time referenced to RAS	60	-	75		ns	
tREF	Refresh Period	_	16	_	16	ms	
twcs	Write Command Set-Up Time	0	_	0	-	ns	13
^t CWD	CAS to WRITE Delay Time	20	_	25	_	ns	13
^t RWD	RAS to WRITE Delay Time	80	-	100	_	ns	13
^t AWD	Column Address to WRITE Delay Time	40	_	50	_	ns	13
^t CSR	CAS Set-Up Time (CAS before RAS Cycle)	5	_	5	_	ns	
^t CHR	CAS Hold Time (CAS before RAS Cycle)	15		20	_	ns	
^t RPC	RAS to CAS Precharge Time	0	_	0	_	ns	
^t CPT	CAS Precharge Time (CAS before RAS Counter Test Cycle)	40	-	50	-	ns	
^t NCAS	Nibble Mode Pulse Width	20		25		ns	
tNCP	Nibble Mode CAS Precharge Time	10		10		ns	
^t NRSH	Nibble Mode RAS Hold Time	20		25	-	ns	
^t NCWD	Nibble Mode CAS to WRITE Delay Time	20		25		ns	
	Nibble Mode WRITE Command to RAS Lead Time	20	-	25	-	ns	
- NI.WI. I	Nibble Mode WRITE Command to CAS Lead Time	20	-	25	-	ns	
^t WTS	Write Command Set-Up Time (Test Mode In)	10	_	10		ns	
^t WTH	Write Command Hold Time (Test Mode In)	10		10		ns	
t _{WRP}	WRITE to RAS Precharge Time (CAS before RAS Cycle)	10	-	10	-	ns	
	WRITE to RAS Hold Time (CAS before RAS Cycle)	10	-	10	-	ns	

ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS IN THE TEST MODE

 $(V_{CC}=5V\pm10\%, Ta=0\sim70^{\circ}C)$ (Note 6, 7, 8)

SYMBOL	PARAMETER		TC514101J/Z -80		TC514101J/Z -10		NOTES
		MIN.	MAX.	MIN.	MAX.		İ
tRC	Random Read or Write Cycle Time	155	-	185	1	ns	
^t RAC	Access Time from RAS	-	85	1	105	ns	9,14.15
^t CAC	Access Time from CAS	_	25	-	30	ns	9,14
t _{AA}	Access Time from Column Address	-	45	•	55	ns	9,15
t _{RAS}	RAS Pulse Width	85	10,000	105	10,000	ns	
tRSH	RAS Hold Time	25	-	30	_	ns	
t _{CSH}	CAS Hold Time	85	-	105	-	ns	
tCAS	CAS Pulse Width	25	10,000	30	10,000	ns	
t _{RAL}	Column Address to RAS Lead Time	45		55	-	ns	<u> </u>

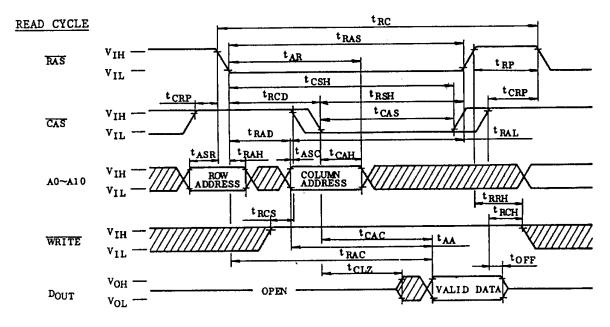
CAPACITANCE ($V_{CC}=5V\pm10\%$, f=1MHz, Ta=0 $\sim70^{\circ}$ C)

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
CIl	Input Capacitance (A0 ~ A10, DIN)	-	5	pF
C ₁₂	Input Capacitance (RAS, CAS, WRITE)	-	7	pF
CO	Output Capacitance (DOUT)		7	pF

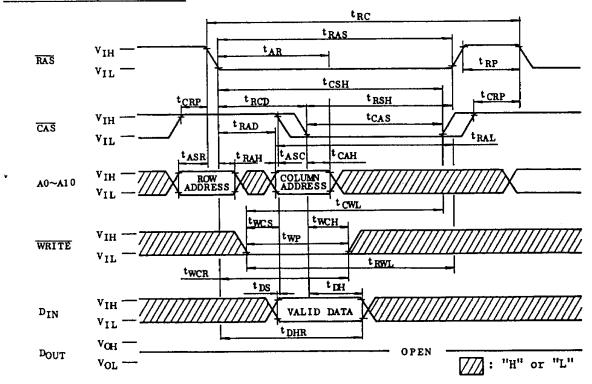
NOTES:

- 1. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device.
- 2. All voltages are referenced to VSS.
- I_{CC1}, I_{CC3}, I_{CC4}, I_{CC6} depend on cycle rate.
- I_{CC1}, I_{CC4} depend on output loading. Specified values are obtained with the output open.
- 5. Column address can be changed once or less while RAS=VIL and CAS=VIH.
- 6. An initial pause of 200 μ s is required after power-up followed by 8 RAS only refresh cycles before proper device operation is achieved. In case of using internal refresh counter, a minimum of 8 CAS before RAS refresh cycles instead of 8 RAS only refresh cycles are required.
- 7. AC measurements assume t_T =5ns.
- 8. $V_{\rm IH}({\rm min.})$ and $V_{\rm IL}({\rm max.})$ are reference levels for measuring timing of input signals. Also, transition times are measured between $V_{\rm IH}$ and $V_{\rm IL}$.
- 9. Measured with a load equivalent to 2 TTL loads and 100pF.
- 10. toff(max.) defines the time at which the output achieves the open circuit condition and is not referenced to output voltage levels.
- 11. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
- 12. These parameters are referenced to $\overline{\text{CAS}}$ leading edge in early write cycles and to $\overline{\text{WRITE}}$ leading edge in read-modify-write cycles.
- 13. twcs, trwd, tcwd and tawd are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If twcs ≥ twcs (min.), the cycle is an early write cycle and data out pin will remain open circuit (high impedance) through the entire cycle; If trwd ≥ trwd (min.), tcwd ≥ tcwd (min.) and tawd ≥ tawd (min.), the cycle is a read-modify-write cycle and data out will contain data read from the selected cell: If neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
- 14. Operation within the $t_{RCD}(max.)$ limit insures that $t_{RAC}(max.)$ can be met. $t_{RCD}(max.)$ is specified as a reference point only: If t_{RCD} is greater than the specified $t_{RCD}(max.)$ limit, then access time is controlled by t_{CAC} .
- 15. Operation within the $t_{RAD}(max.)$ limit insures that $t_{RAC}(max.)$ can be met. $t_{RAD}(max.)$ is specified as a reference point only: If t_{RAD} is greater than the specified $t_{RAD}(max.)$ limit, then access time is controlled by t_{AA} .

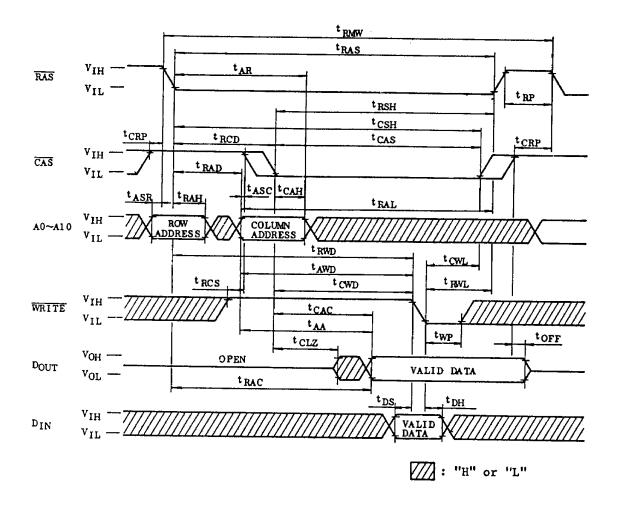
TIMING WAVEFORMS



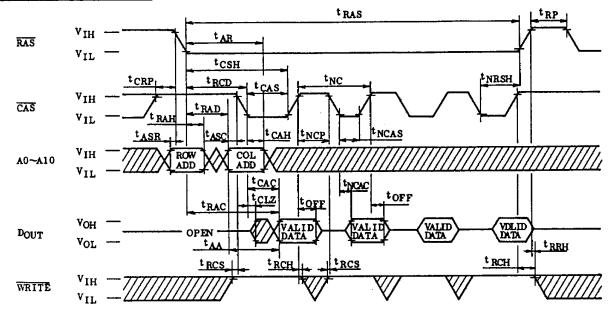
WRITE CYCLE (EARLY WRITE)



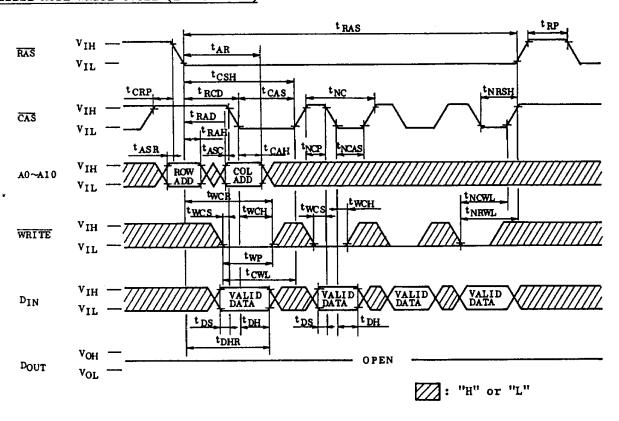
READ-MODIFY-WRITE CYCLE



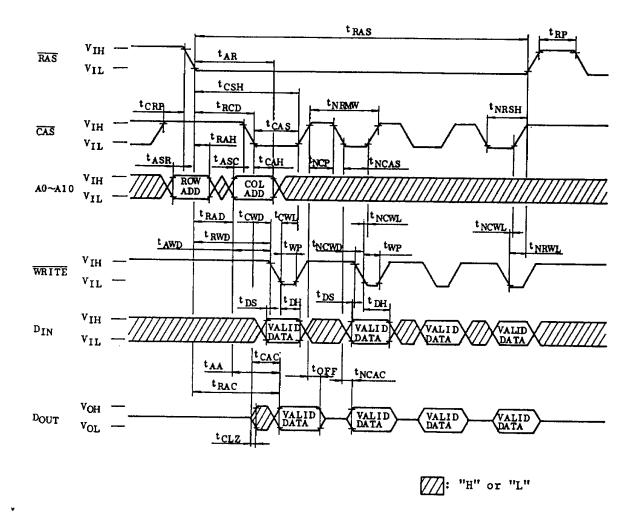
NIBBLE MODE READ CYCLE



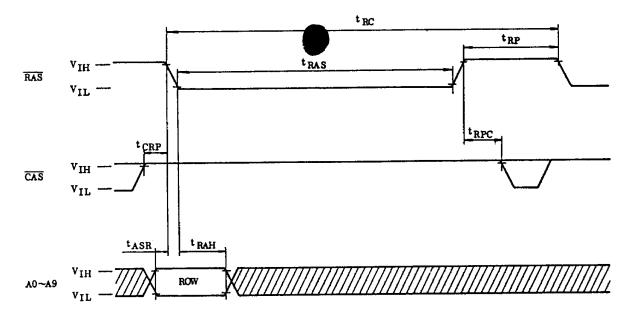
NIBBLE MODE WRITE CYCLE (EARLY WRITE)



NIBBLE MODE READ-MODIFY-WRITE CYCLE



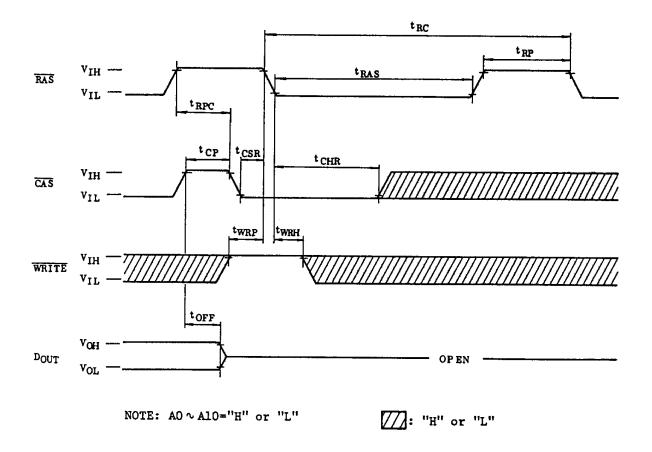
RAS ONLY REFRESH CYCLE



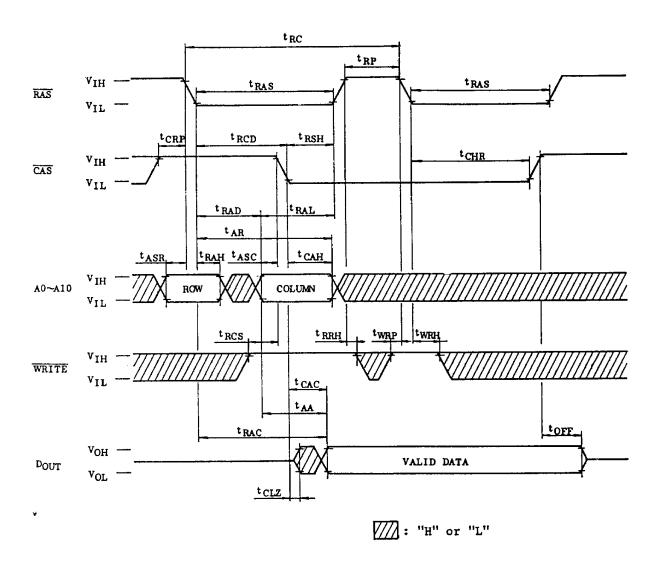
: "H" or "L"

NOTE: WRITE="H" or "L" , AlO="H" or "L"

CAS BEFORE RAS REFRESH CYCLE

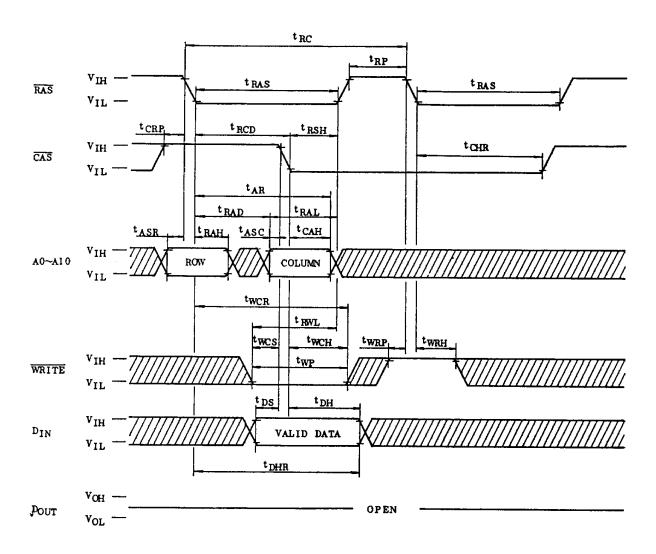


HIDDEN REFRESH CYCLE (READ)



A-149

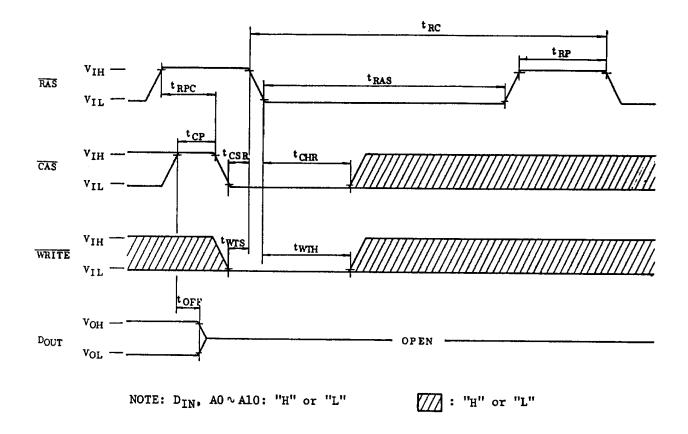
HIDDEN REFRESH CYCLE (WRITE)



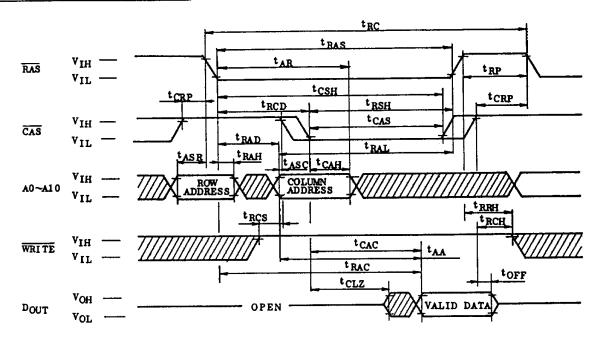
. "H" or "L"

CAS BEFORE RAS REFRESH COUNTER TEST CYCLE t_{RAS} v_{IH} t RSH RAS tCPT CAS COLUMN t_{CAC} t_{RAL} READ CYCLE toff OPEN VALID DATA $\mathbf{D}_{\!OUT}$ tRRH t_{RCS} WRITE WRITE CYCLE DOUT - OPEN t RWL t_{CWL} twRP twRH twcs twcH. WRITE t_{DH} VALID DATA p_{IN} t CAC READ-MODIFY-WRITE CYCLE t OFF v_{OH} — DOUT - OPEN VALID DATA t CWL tAWD WRITE t CWD VALID DATA D_{IN} t DH t DS : "H" or "L"

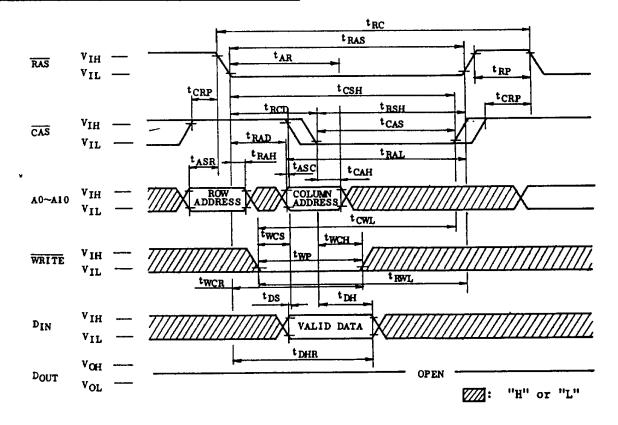
WRITE, CAS BEFORE RAS REFRESH CYCLE



READ CYCLE IN THE TEST MODE



WRITE CYCLE (EARLY WRITE) IN THE TEST MODE



APPLICATION INFORMATION

ADDRESSING

The 22 address bits required to decode 1 of the 4,194,304 cell locations within the TC514101J/Z are multiplexed onto the 11 address inputs and latched into the on-chip address latches by externally applying two negative going TTL-level clocks.

The first clock, the Row Address Strobe (\overline{RAS}), latches the ll row address bits into the chip. The second clock, the Column Address Strobe (\overline{CAS}), subsequently latches the ll column address bits into the chip. Each of these signals, \overline{RAS} , and \overline{CAS} , triggers a sequence of events which are controlled by different delayed internal clocks.

The two clock chains are linked together logically in such a way that the address multiplexing operation is done outside of the critical path timing sequence for read data access. The later events in the $\overline{\text{CAS}}$ clock sequence are inhibited until the occurrence of a delayed signal derived from the $\overline{\text{RAS}}$ clock chain. This "gated $\overline{\text{CAS}}$ " feature allows the $\overline{\text{CAS}}$ clock to be externally activated as soon as the Row Address Hold Time specification (trah) has been satisfied and the address inputs have been changed from Row address to Column address information.

DATA INPUT/OUTPUT

Data to be written into a selected cell is latched into an on-chip register by a combination of WRITE and CAS while RAS is active. The later of the signals (WRITE or CAS) to make its negative transition is the strobe for the Data In (D_{IN}) register. This permits several options in the write cycle timing. In a write cycle, if the WRITE input is brought low (active) prior to CAS, the D_{IN} is strobed by CAS and the set-up and hold times are referenced to CAS. If the input data is not available at CAS time or if it is desired that the cycle be a read-write cycle, the WRITE signal will be delayed until after CAS has made its negative transition. In this "delayed write cycle" the data input set-up and hold times are referenced to the negative edge of WRITE rather than CAS. (To illustrate this feature, D_{IN} is referenced to WRITE in the timing diagrams depicting the read-write and nibble mode write cycles while the "early write" cycle diagram shows D_{IN} referenced to CAS).

Data is retrieved from the memory in a read cycle by maintaining WRITE in the inactive or high state throughout the portion of the memory cycle in which CAS is active (low). Data read from the selected cell will be available at the outtut within the specified access time.

DATA OUTPUT CONTROL

The normal condition of the Data Output (D_{OUT}) of the TC514101J/Z is the high impedance (open circuit) state. This is to say, anytime \overline{CAS} is at a high level, the D_{OUT} pin will be floating. The only time the output will turn on and contain either a logic 0 or logic 1 is at access time during a read cycle. D_{OUT} will remain valid from access time until \overline{CAS} is taken back to the inactive (high level) condition.

NIBBLE MODE

Nibble mode operation allows faster successive data operation on 4 bits. The first of 4 bits is accessed in the usual manner with read data coming out at t_{CAC} time. By keeping \overline{RAS} low, \overline{CAS} can be cycled up and then down, to read or write the next three pages at high data rate. Row and column address need only be supplied for the first access of the cycles. From then on, the falling edge of \overline{CAS} will activate the next bit. After four bits have been accessed, the next bit will be the same as the first bit accessed (wrap-around method).

$$(0, 0) \longrightarrow (0, 1) \longrightarrow (1, 0) \longrightarrow (1, 1) \longrightarrow$$

Address AlO determines the starting point of the circular 4 bits nibble. Row AlO and column AlO provide the two binary bits needed to select one of four bits. From then on, successive bits come out in a binary fashion; $00 \rightarrow 01 \rightarrow 10 \rightarrow 11$ with AlO row being the least significant address.

A nibble cycle can be a read, write, or delayed write cycle. Any combinations of reads and writes or late writes will be allowed. In addition, the circular wraparound will continue for as long as \overline{RAS} is kept low.

RAS ONLY REFRESH

Refresh of the dynamic cell matrix is accomplished by performing a memory cycle at each of the 1024 row address (A0 $^{\sim}$ A9) within each 16 millisecond time interval. Although any normal memory cycle will perform the refresh operation, this function is most easily accomplished with " $\overline{\text{RAS}}$ -only" cycles.

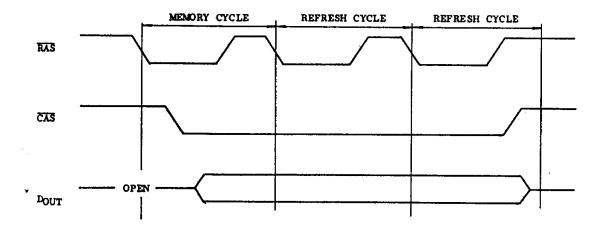


CAS BEFORE RAS REFRESH

 $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refreshing available on the TC514101J/Z offers an alternate refresh method. If $\overline{\text{CAS}}$ is held on low for the specified period (t_{CSR}) before $\overline{\text{RAS}}$ goes to low, on chip refresh control clock generators and the refresh address counter are enabled, and an internal refresh operation takes place. After the refresh operation is performed, the refresh address counter is automatically incremented in preparation for the next $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh operation.

HIDDEN REFRESH

An optional feature of the TC514101J/Z is that refresh cycles may be performed while maintaining valid data at the output pin. This referred to as Hidden Refersh. Hidden Refresh is performed by holding $\overline{\text{CAS}}$ at V_{IL} and taking $\overline{\text{RAS}}$ high and after a specified precharge period (t_{RP}), executing a $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh cycle. (See Figure below)



This feature allows a refresh cycle to be "hidden" among data cycles without affecting the data availability.

CAS BEFORE RAS REFRESH COUNTER TEST

The internal refresh operation of TC514101J/Z can be tested by CAS BEFORE RAS
REFRESH COUNTER TEST. This cycle performs READ/WRITE operation taking the internal
counter address as row address and the input address as column address.

The test is performed after a minimum of 8 CAS before RAS cycles as initialization cycles. The test procedure is as follows.

- (1) Write "0" into all the memory cells at normal write mode.
- ② Select one certain column address and read "0" out and write "1" in each cell by performing CAS BEFORE RAS REFRESH COUNTER TEST (READ-WRITE CYCLE).

 Repeat this operation 1024 times.
- (3) Check "1" out of 1024 bits at normal read mode, which was written at (2).
- 4 Using the same column as 2, read "1" out and write "0" in each cell performing CAS BEFORE RAS REFRESH COUNTER TEST.

 Repeat this operation 1024 times.
- (5) Check "0" out of 1024 bits at normal read mode, which was written at 4.
- 6 Perform the above 1 to 5 the complement data.



TEST MODE

The TC514101J/Z is the RAM organized 4,194,304 words by 1 bit, it is internally organized 524,288 words by 8 bits. In "Test Mode", data are written into 8 sectors in parallel and retrieved the same way. AlOR, AlOC and AOC are not used. If, upon reading, all bits are equal (all "l"s or "O"s), the data output pin indicates a "l". If any of the bits differed, the data output pin would indicate a "O". Fig. 1 shows the block diagram of TC514101J/Z. In "Test Mode", the 4M DRAM can be tested as if it were a 512K DRAM.

"WRITE, CAS Before RAS Refresh Cycle" puts the device into "Test Mode". And "CAS Before RAS Refresh Cycle" or "RAS Only Refresh Cycle" puts it back into "Normal Mode". In the Test Mode, "WRITE, CAS Before RAS Refresh Cycle" performs the refresh operation with the internal refresh address counter. The "Test Mode" function reduces test times (1/8 in case of N test pattern).

BLOCK DIAGRAM IN TEST MODE

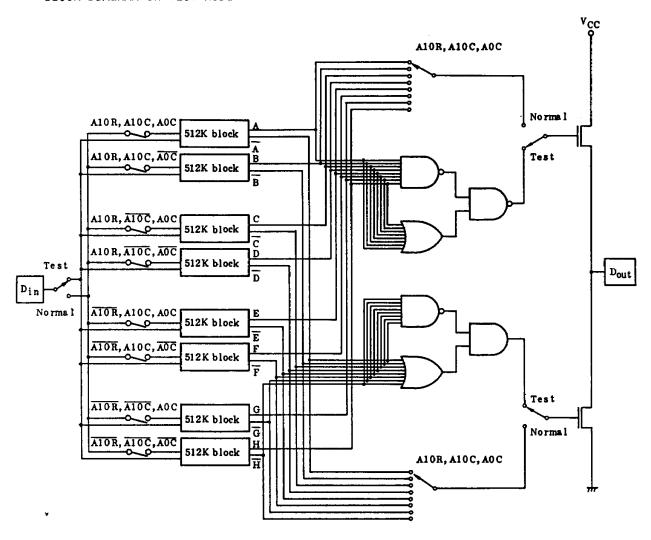


Fig. 1